

CMOS MMIC 4 x 2 IF SWITCH MATRIX

FEATURES

- 4 independent IF channels, integral switching to channel input to either channel output
- Integrated 4 bit decoder
- Frequency range : $f = 250$ to $2\,150$ MHz
- High isolation D/U ratio : $ISL = 29$ dB TYP.
- Insertion loss : $L_{INS} = 6.7$ dB TYP. @ $Z_0 = 50\ \Omega$
- Insertion loss flatness : $\Delta L_{INS} = 0.7$ dB TYP.
- Control voltage : $V_{CONT} = 0\text{ V}/+3.3\text{ V}$
- 16-pin plastic HTSSOP package

APPLICATIONS

- DBS IF switching
- Switch box
- 4×2 switching application for microwave signal

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μ PD5715GR-E1	μ PD5715GR-E1-A	16-pin plastic HTSSOP (Pb-Free)	D5715	<ul style="list-style-type: none">• Embossed tape 12 mm wide• Pin 8, 9 face the perforation side of the tape• Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: μ PD5715GR

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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ABSOLUTE MAXIMUM RATINGS ($T_A = +25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V_{DD}	+4.6	V
Switch Control Voltage 1 to 4	$V_{CONT1\text{ to }4}$	+4.6	V
Total Power Dissipation	P_{tot}	2 ^{Note}	W
Input Power	P_{in}	+15	dBm
Operating Ambient Temperature	T_A	-40 to +85	$^\circ\text{C}$
Storage Temperature	T_{stg}	-65 to +150	$^\circ\text{C}$

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, $T_A = +85^\circ\text{C}$

RECOMMENDED OPERATING CONDITIONS ($T_A = +25^\circ\text{C}$)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V_{DD}	+3.0	+3.3	+3.6	V
Control Voltage (H) ^{Note}	$V_{CONT(H)}$	+3.0	+3.3	+3.6	V
Control Voltage (L)	$V_{CONT(L)}$	-0.2	0	+0.4	V

Note $V_{DD} - 0.4\text{ V} \leq V_{CONT(H)} \leq V_{DD} + 0.2\text{ V}$

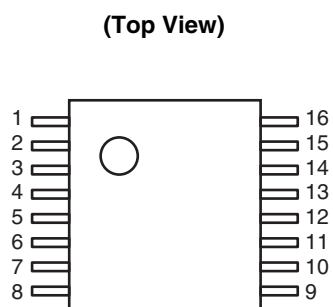
ELECTRICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$, $V_{DD} = +3.3\text{ V}$, $V_{CONT} = 0\text{ V}/+3.3\text{ V}$, $P_{in} = 0\text{ dBm}$, $Z_o = 50\ \Omega$, each port, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	L_{INS}	$f = 0.25$ to 2.15 GHz	—	6.7	9.0	dB
Insertion Loss Flatness	ΔL_{INS}	$ L_{INS}(0.95\text{ GHz}) - L_{INS}(2.15\text{ GHz}) $	—	0.7	3.0	dB
Isolation D/U-ratio1 ^{Note 1}	ISL1	$f = 0.25$ to 0.95 GHz	28	34	—	dB
Isolation D/U-ratio2 ^{Note 1}	ISL2	$f = 0.95$ to 2.15 GHz	25	29	—	dB
Output Return Loss	RL_{out}	$f = 0.25$ to 2.15 GHz	10	13	—	dB
Control Current ^{Note 2}	I_{CONT}	$V_{DD} = +3.3\text{ V}$, $V_{CONT} = +3.3\text{ V}/0\text{ V}$, non-RF	—	0.01	1	μA
Supply Current	I_{DD}	$V_{DD} = +3.3\text{ V}$, $V_{CONT} = +3.3\text{ V}/0\text{ V}$, non-RF	—	0.01	1	μA

Notes 1. Isolation Desire Un-desire (D/U)-ratio = $|(Signal\ leakage\ (off-state)) - (Insertion\ loss\ (on-state))|$

2. Per 1 control pin

PIN CONNECTIONS



Pin No.	Pin Name	Pin No.	Pin Name
1	IN-C	16	IN-B
2	GND	15	GND
3	IN-D	14	IN-A
4	GND	13	GND
5	GND	12	V _{DD}
6	OUT2	11	OUT1
7	V _{CONT3}	10	V _{CONT1}
8	V _{CONT4}	9	V _{CONT2}

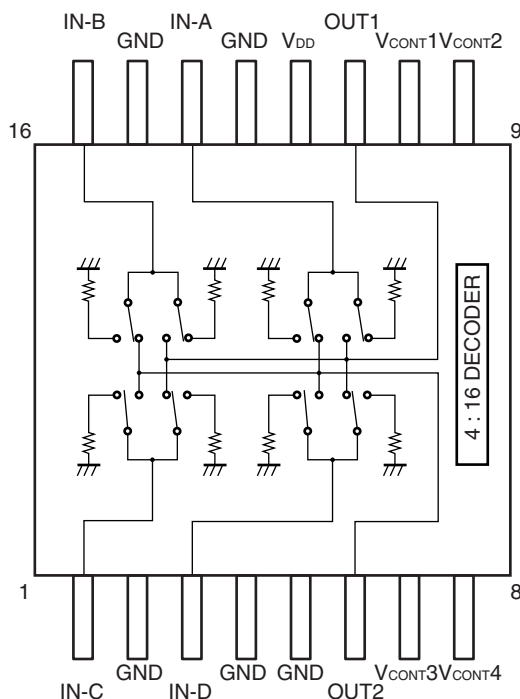
Remark Back side. : GND

TRUTH TABLE

State		Output Signal		Control Pins			
No.	Mode	OUT1	OUT2	V _{CONT1}	V _{CONT2}	V _{CONT3}	V _{CONT4}
1	AA	IN-A	IN-A	Low	Low	Low	Low
2	AB		IN-B	Low	Low	Low	High
3	AC		IN-C	Low	Low	High	Low
4	AD		IN-D	Low	Low	High	High
5	BA	IN-B	IN-A	Low	High	Low	Low
6	BB		IN-B	Low	High	Low	High
7	BC		IN-C	Low	High	High	Low
8	BD		IN-D	Low	High	High	High
9	CA	IN-C	IN-A	High	Low	Low	Low
10	CB		IN-B	High	Low	Low	High
11	CC		IN-C	High	Low	High	Low
12	CD		IN-D	High	Low	High	High
13	DA	IN-D	IN-A	High	High	Low	Low
14	DB		IN-B	High	High	Low	High
15	DC		IN-C	High	High	High	Low
16	DD		IN-D	High	High	High	High

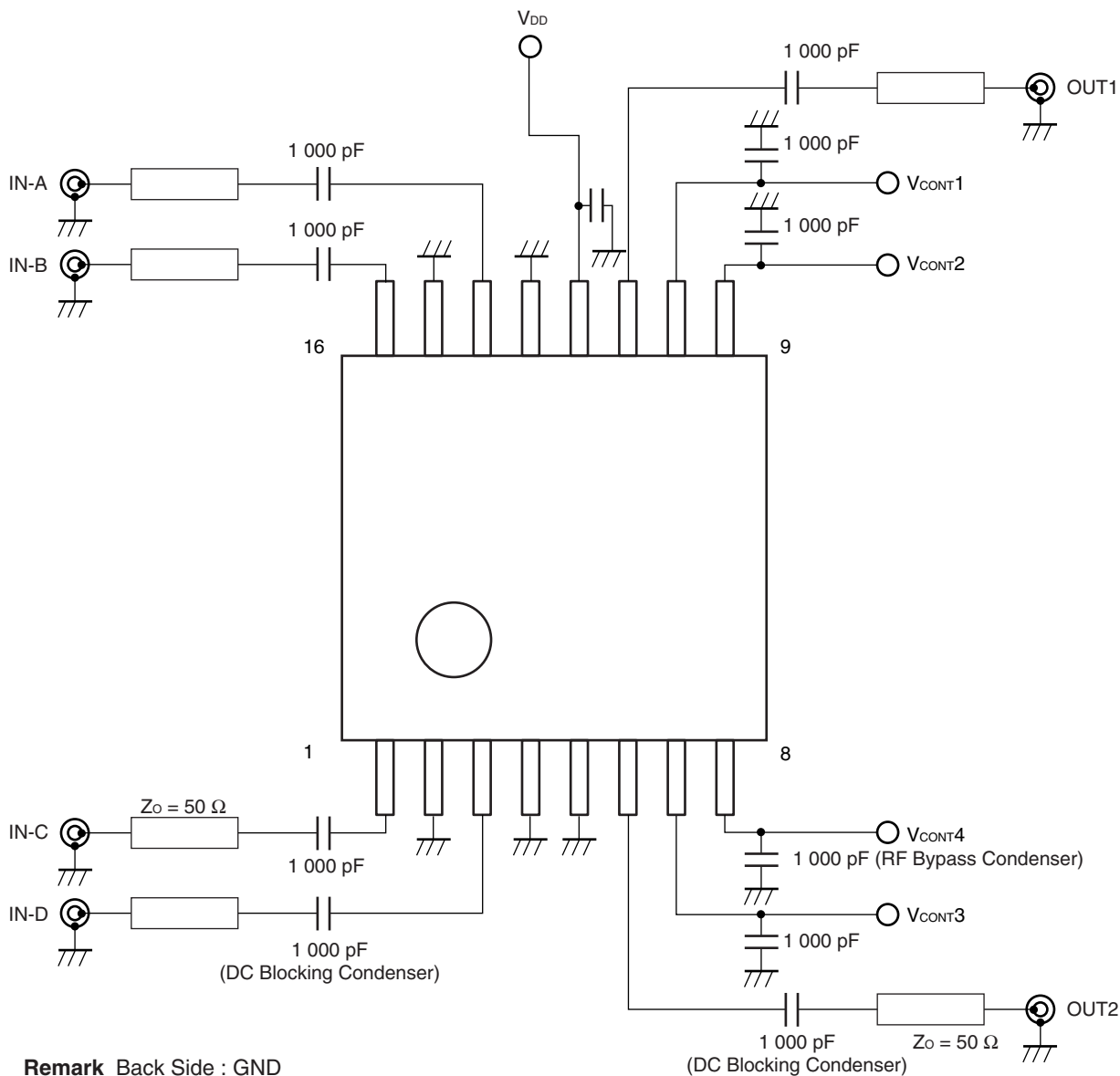
Remark High : +3.3 Vdc, Low : 0 Vdc

FUNCTIONAL DIAGRAM



Remark Back Side : GND

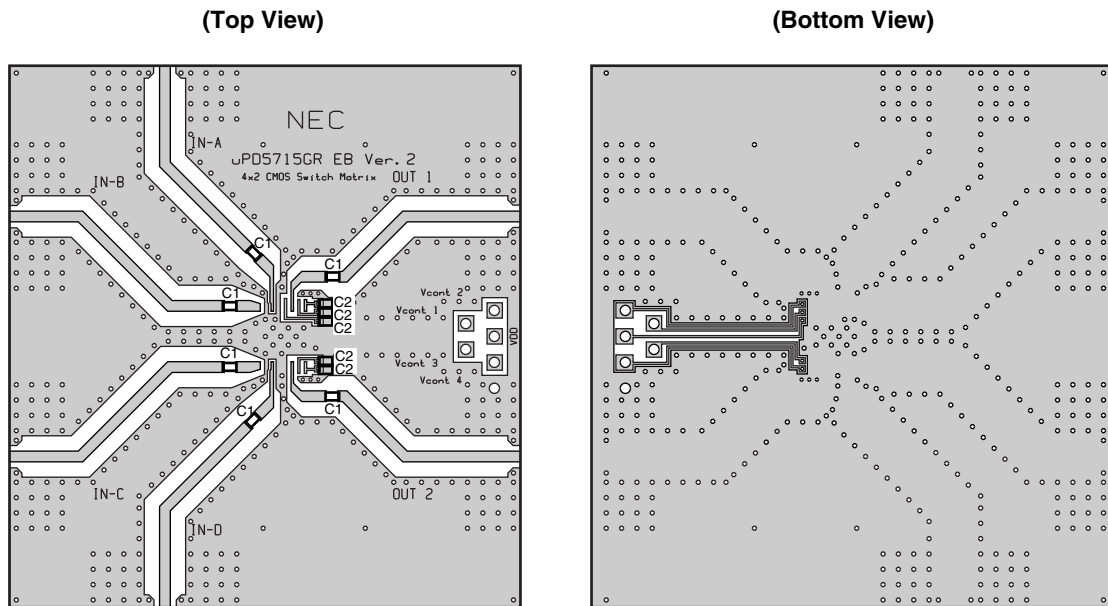
EVALUATION CIRCUIT ($V_{DD} = +3.3\text{ V}$, V_{CONT1} to $V_{CONT4} = 0\text{ V}/+3.3\text{ V}$, $P_{in} = 0\text{ dBm}$, $Z_o = 50\ \Omega$, DC Blocking Capacitor = 1 000 pF)



Remark Back Side : GND

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

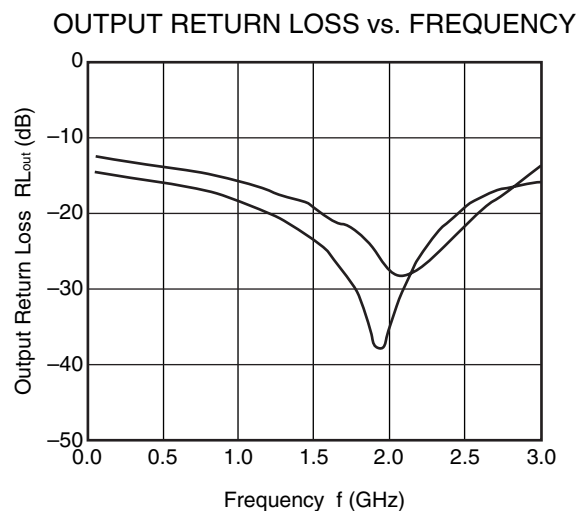
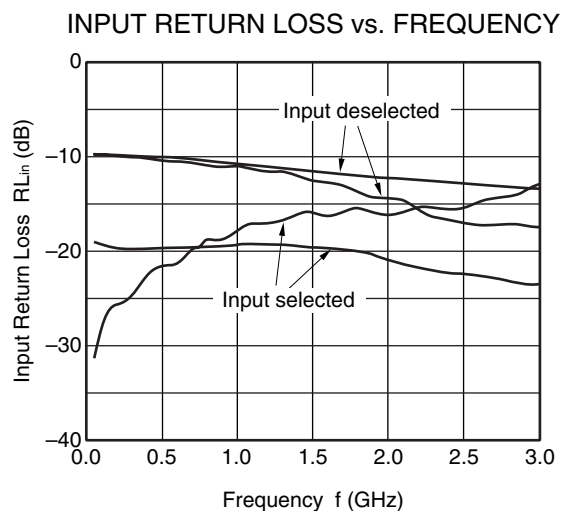
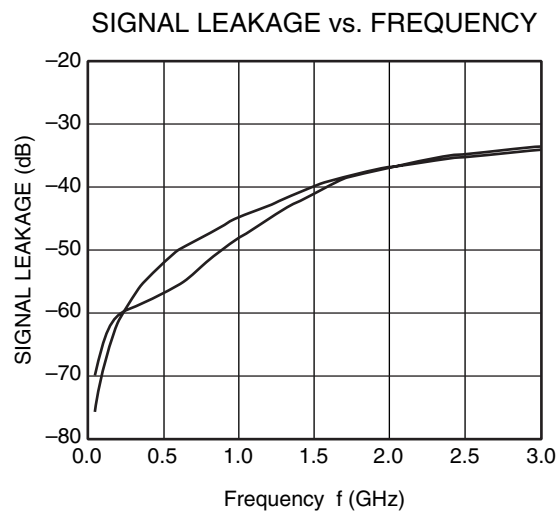
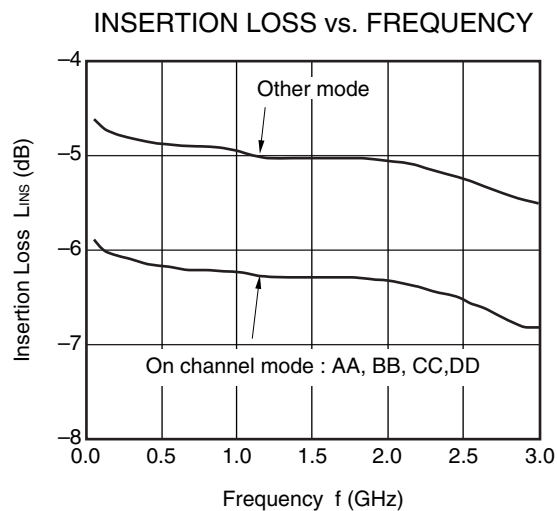


Notes

1. 50 × 53 × 0.51 mm double sided copper clad RO4003 (Rogers) board ($\epsilon_r = 3.38$).
2. Au plated on pattern
3. \circ : Through holes
4. C1, C2: 1 000 pF

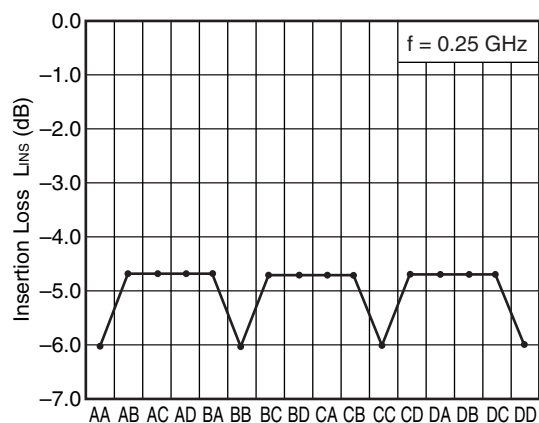
TYPICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{DD} = +3.3\text{ V}$, $V_{CONT} = 0\text{ V}/+3.3\text{ V}$, $P_{in} = 0\text{ dBm}$, $Z_o = 50\ \Omega$, unless otherwise specified)



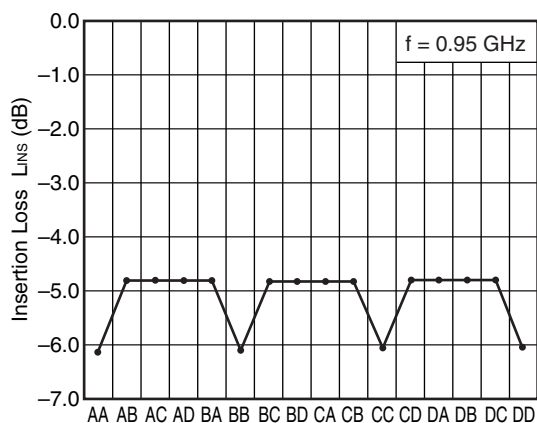
Remark The graphs indicate nominal characteristics.

INSERTION LOSS vs.
ON CHANNEL MODE



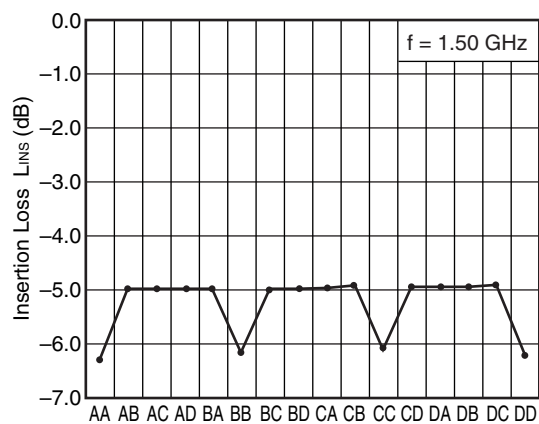
ON CHANNEL MODE

INSERTION LOSS vs.
ON CHANNEL MODE



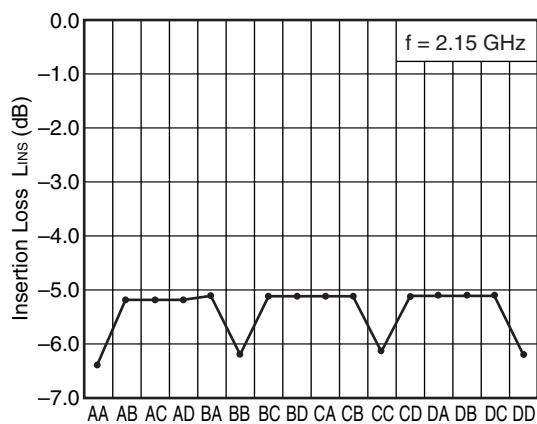
ON CHANNEL MODE

INSERTION LOSS vs.
ON CHANNEL MODE



ON CHANNEL MODE

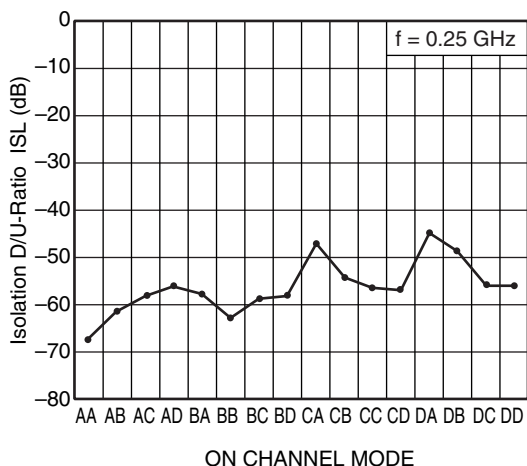
INSERTION LOSS vs.
ON CHANNEL MODE



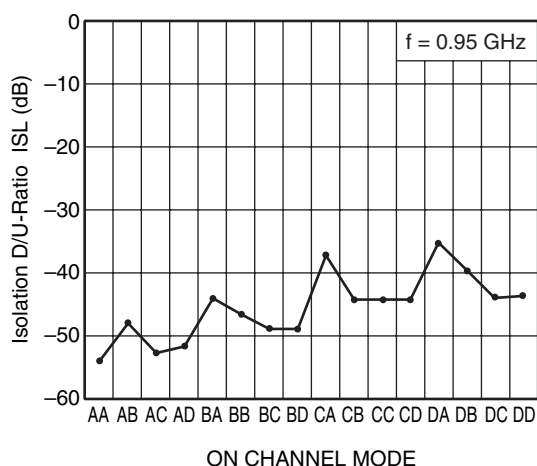
ON CHANNEL MODE

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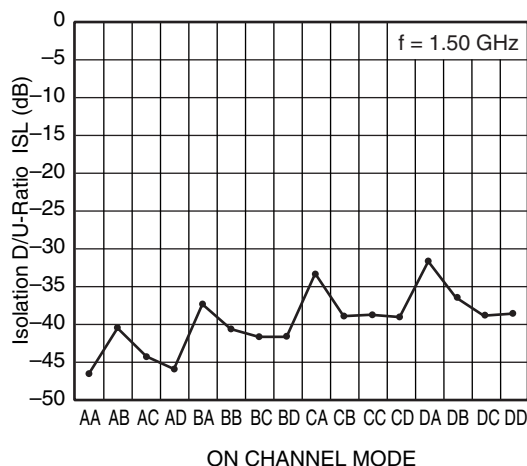
ISOLATION D/U-RATIO
vs. ON CHANNEL MODE



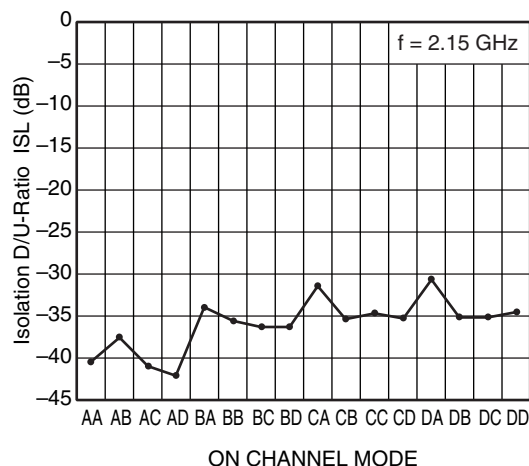
ISOLATION D/U-RATIO
vs. ON CHANNEL MODE



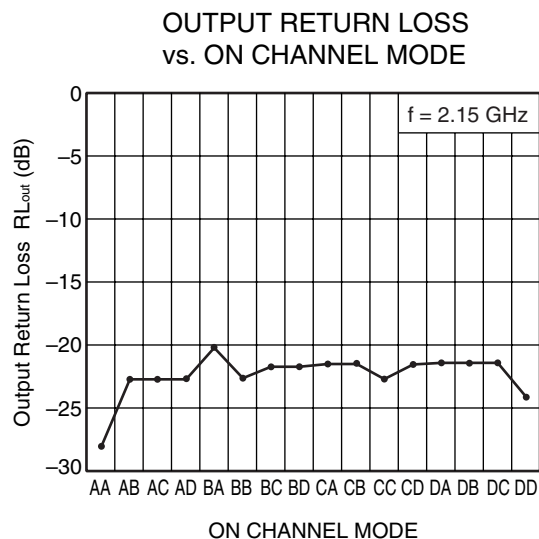
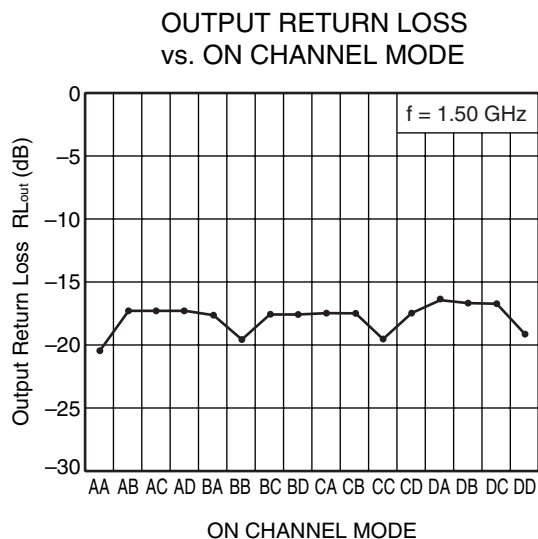
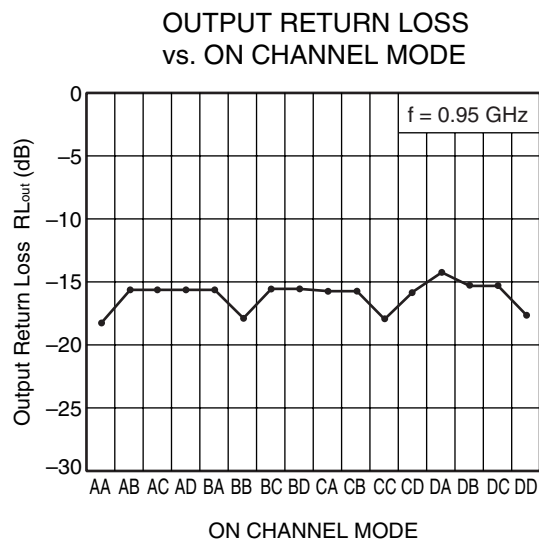
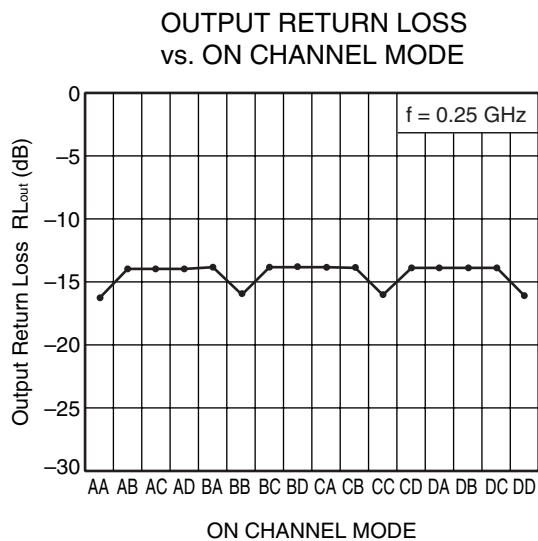
ISOLATION D/U-RATIO
vs. ON CHANNEL MODE



ISOLATION D/U-RATIO
vs. ON CHANNEL MODE



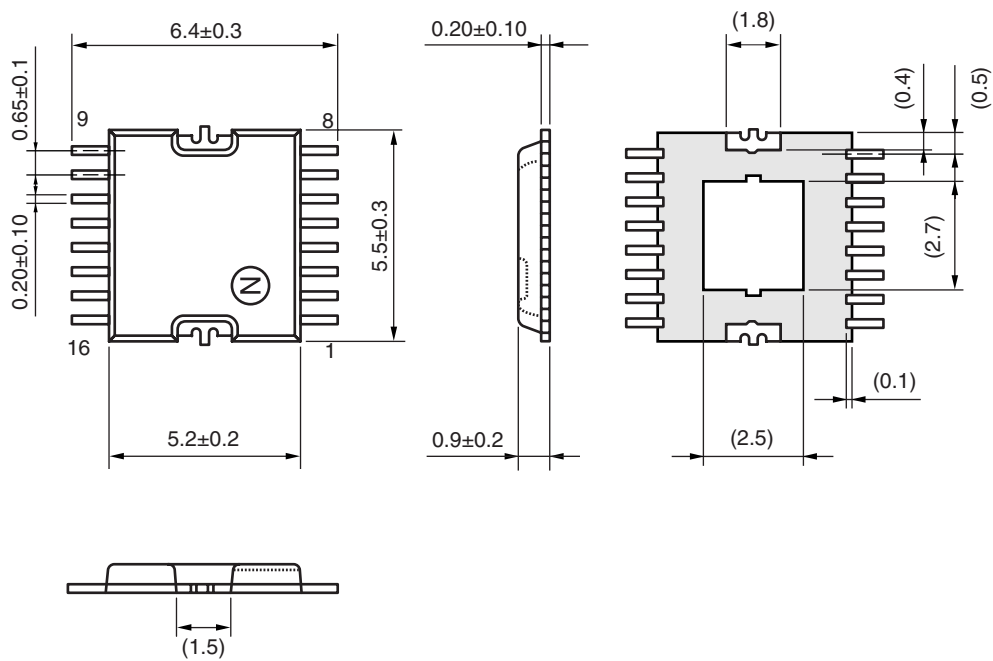
Remark The graphs indicate nominal characteristics.



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PACKAGE DIMENSIONS

16-PIN PLASTIC HTSSOP (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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